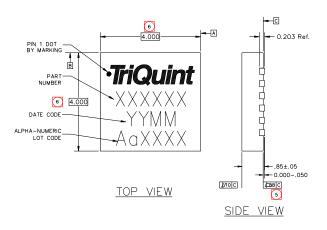
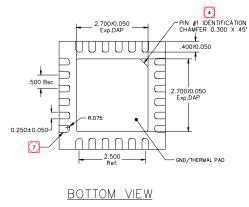


Mechanical Information

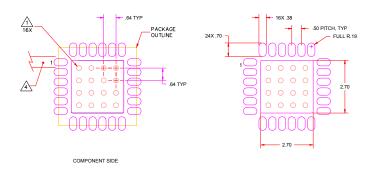
Package Information and Dimensions

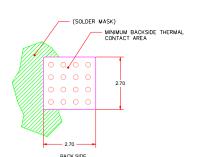
The component will be marked with a "7M9106" designator and an alphanumeric lot code on the top surface of package.





PCB Mounting Pattern





NOTES:

- GROUND/THERMAL WAS ARE CRITICAL FOR THE PROPER PERFORMANCE OF THIS DEVICE. WAS SHOULD USE A .35mm (#80/.0135") DIAMETER DRILL AND HAVE A FINAL, PLATED THRU DIAMETER OF .25mm (.010").
- ADD AS MUCH COPPER AS POSSIBLE TO INNER AND OUTER LAYERS NEAR THE PART TO ENSURE OPTIMAL THERMAL PERFORMANCE.
- LAYERS NEAR THE PART TO ENSURE OPTIMAL THERMAL PERFORMANCE.

 3. TO ENSURE RELIABLE OPERATION, DEVICE GROUND PADDLE-TO-GROUND PAD SOLDER JOINT IS CRITICAL.
- AND CONSTRUCTION.
- 5. USE 1 OZ. COPPER MINIMUM.
- 6. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

NOTES:

- 1. All dimensions are in millimeters [inches]. Angles are in degrees.
- 2. Use 1 oz. copper minimum for top and bottom layer metal.
- Vias are required under the backside paddle of this device for proper RF/DC grounding and thermal dissipation. We recommend a 0.35mm (#80/.0135") diameter bit for drilling via holes and a final plated thru diameter of 0.25mm (0.10").
- 4. Ensure good package backside paddle solder attach for reliable operation and best electrical performance.
- 5. Place mounting screws near the part to fasten a back side heat sink.
- Do not apply solder mask to the back side of the PC board in the heat sink contact region.
- Ensure that the backside via region makes good physical contact with the heat sink.